

High Power Infrared Emitter (850 nm)

Preliminary Version 0.0

SFH 4278S



Features:

- High Power Infrared LED
- Double Stack emitter
- Half angle: $\pm 15^\circ$
- High forward current allowed at high temperature

Applications

- Industrial applications
- Infrared Illumination for cameras
- IR data transmission
- Sensor technology

Notes

Depending on the mode of operation, these devices emit highly concentrated non visible infrared light which can be hazardous to the human eye. Products which incorporate these devices have to follow the safety precautions given in IEC 60825-1 and IEC 62471.

Ordering Information

Type:	Radiant Intensity I_e [mW/sr] $I_F=100$ mA, $t_p=20$ ms	Ordering Code
SFH 4278S	160 (≥ 63)	Q65112A0075

Note: Measured at a solid angle of $\Omega = 0.01$ sr

Maximum Ratings ($T_A = 25\text{ °C}$)

Parameter	Symbol	Values	Unit
Operation and storage temperature range	$T_{op}; T_{stg}$	-40 ... 100	°C
Reverse voltage	V_R	5	V
Forward current	I_F	100	mA
Surge current ($t_p \leq 300\text{ }\mu\text{s}$, $D = 0$)	I_{FSM}	0.7	A
Power consumption	P_{tot}	245	mW
ESD withstand voltage (acc. to ANSI/ ESDA/ JEDEC JS-001 - HBM)	V_{ESD}	2	kV
Thermal resistance junction - ambient ^{1) page 12}	R_{thJA}	300	K / W
Thermal resistance junction - soldering point ^{2) page 12}	R_{thJS}	140	K / W

Characteristics ($T_A = 25\text{ °C}$)

Parameter		Symbol	Values	Unit
Peak wavelength ($I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$)	(typ)	λ_{peak}	860	nm
Centroid wavelength ($I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$)	(typ)	$\lambda_{centroid}$	850	nm
Spectral bandwidth at 50% of I_{max} ($I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$)	(typ)	$\Delta\lambda$	30	nm
Half angle	(typ)	φ	± 15	°
Dimensions of active chip area	(typ)	L x W	0.3 x 0.3	mm x mm
Rise and fall time of I_e (10% and 90% of $I_{e\max}$) ($I_F = 100\text{ mA}$, $R_L = 50\text{ }\Omega$)	(typ)	t_r, t_f	15	ns
Forward voltage ($I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$)	(typ (max))	V_F	3.1 (≤ 3.6)	V
Forward voltage ($I_F = 700\text{ mA}$, $t_p = 100\text{ }\mu\text{s}$)	(typ (max))	V_F	4 (≤ 5.2)	V
Reverse current ($V_R = 5\text{ V}$)		I_R	not designed for reverse operation	μA
Total radiant flux ($I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$)	(typ)	Φ_e	95	mW

Parameter		Symbol	Values	Unit
Temperature coefficient of I_e or Φ_e ($I_F = 100$ mA, $t_p = 20$ ms)	(typ)	TC_I	-0.5	% / K
Temperature coefficient of V_F ($I_F = 100$ mA, $t_p = 20$ ms)	(typ)	TC_V	-2	mV / K
Temperature coefficient of wavelength ($I_F = 100$ mA, $t_p = 20$ ms)	(typ)	TC_λ	0.3	nm / K

Grouping ($T_A = 25^\circ\text{C}$)

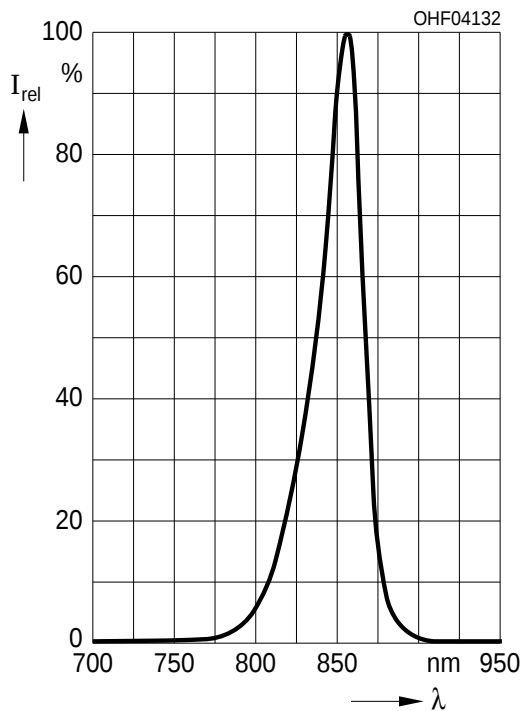
Group	Min Radiant Intensity $I_F=100$ mA, $t_p=20$ ms $I_{e, \min}$ [mW / sr]	Max Radiant Intensity $I_F=100$ mA, $t_p=20$ ms $I_{e, \max}$ [mW / sr]	Typ Radiant Intensity $I_F = 700$ mA, $t_p = 25$ μs $I_{e, \text{typ}}$ [mW / sr]
SFH 4278S-V	63	125	500
SFH 4278S-AW	100	200	795
SFH 4278S-BW	160	320	1270

Note: measured at a solid angle of $\Omega = 0.01$ sr

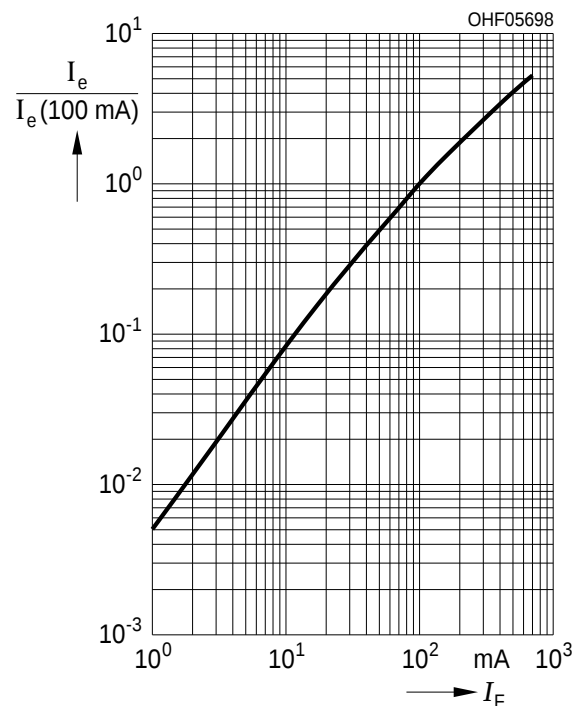
Only one group in one packing unit (variation lower 2:1).

Relative Spectral Emission ^{3) page 12}

$$I_{\text{rel}} = f(\lambda), T_A = 25^\circ\text{C}$$

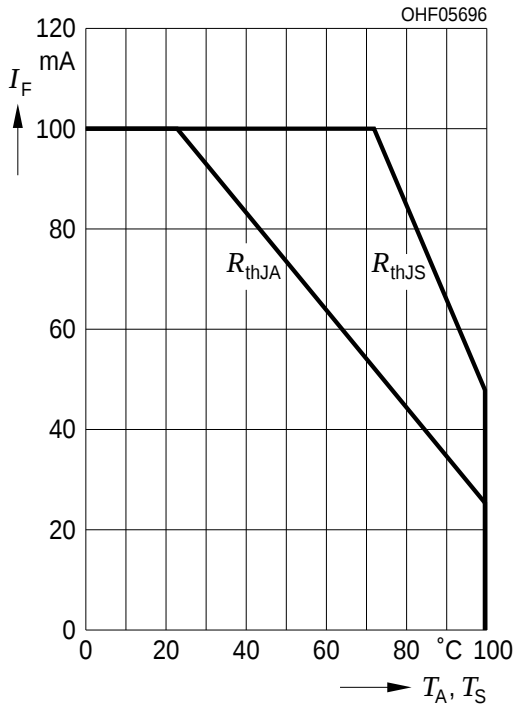
**Radiant Intensity** ^{3) page 12}

$$I_e / I_e(100 \text{ mA}) = f(I_F), \text{ single pulse, } t_p = 25 \mu\text{s}, T_A = 25^\circ\text{C}$$



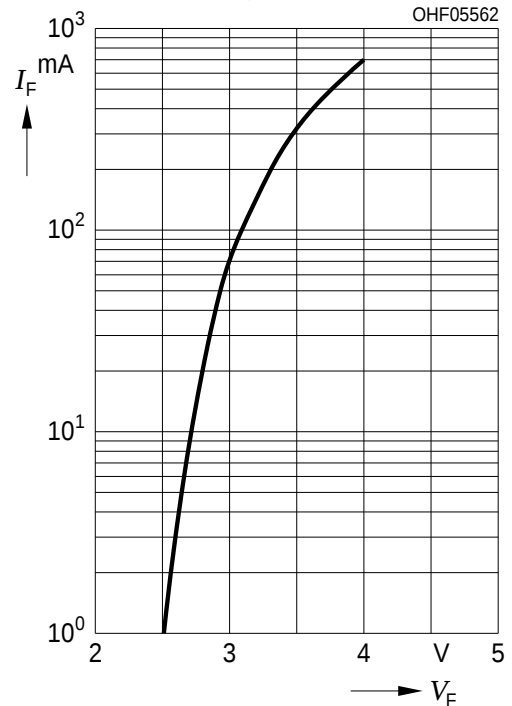
Max. Permissible Forward Current

$$I_{F, \max} = f(T_A), R_{thJA} = 300 \text{ K/W}, R_{thJS} = 140 \text{ K/W}$$



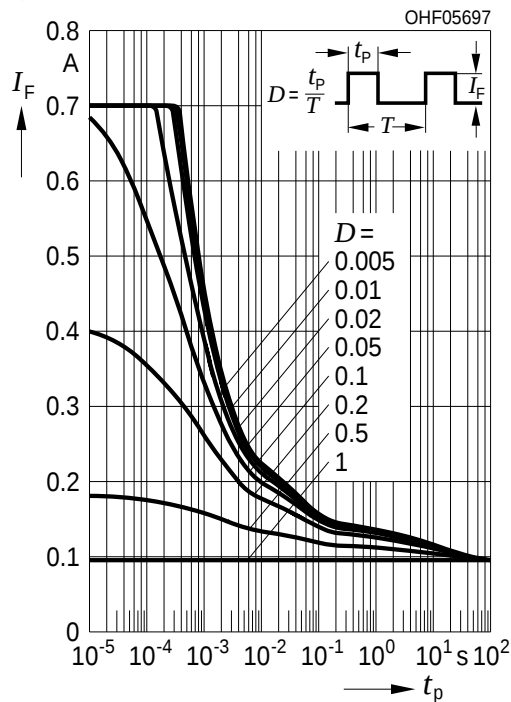
Forward Current ^{3) page 12}

$$I_F = f(V_F), \text{ single pulse, } t_p = 100 \mu\text{s}, T_A = 25^\circ\text{C}$$



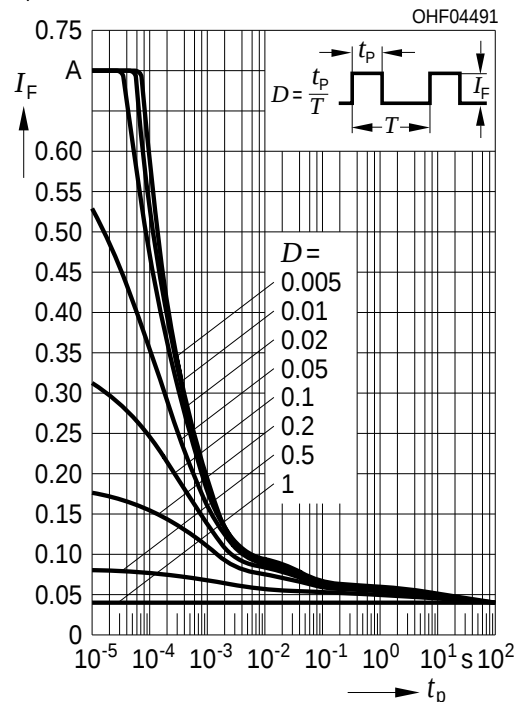
Permissible Pulse Handling Capability

$$I_F = f(t_p), T_A = 25^\circ\text{C}, \text{ duty cycle } D = \text{parameter}$$



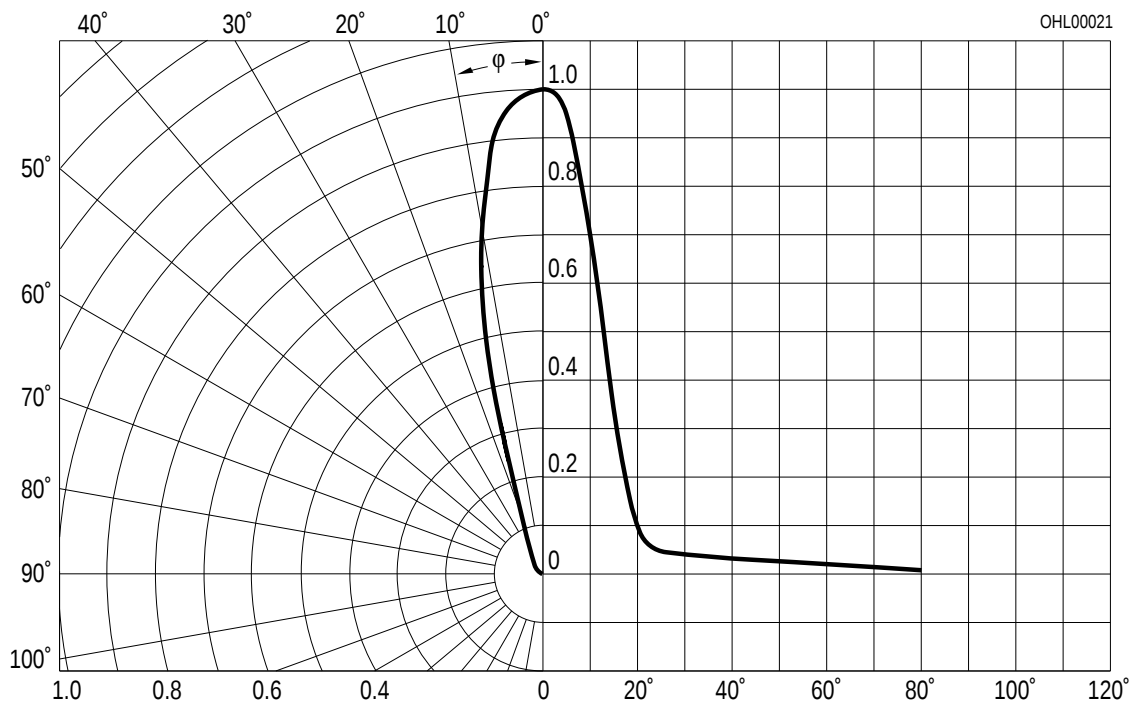
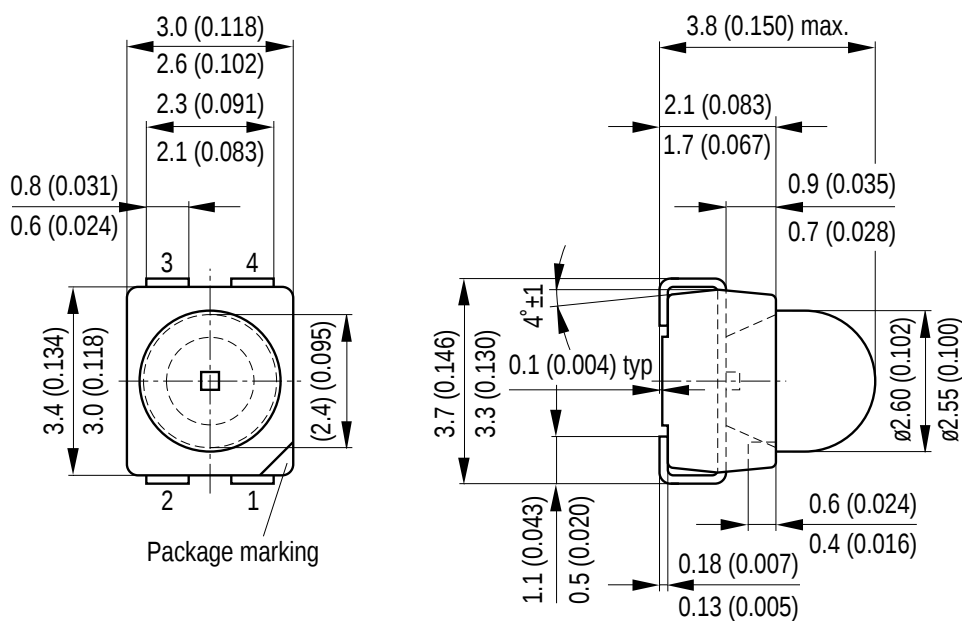
Permissible Pulse Handling Capability

$$I_F = f(t_p), T_A = 85^\circ\text{C}, \text{ duty cycle } D = \text{parameter}$$



Radiation Characteristics ^{3) page 12}

$$I_{\text{rel}} = f(\phi), T_A = 25^\circ\text{C}$$

**Package Outline**

GPLY6127

Dimensions in mm (inch).

Pinning

Pin	Description
1	Cathode
2	Anode
3	Anode
4	Anode

Package

Power TOPLED with Lens

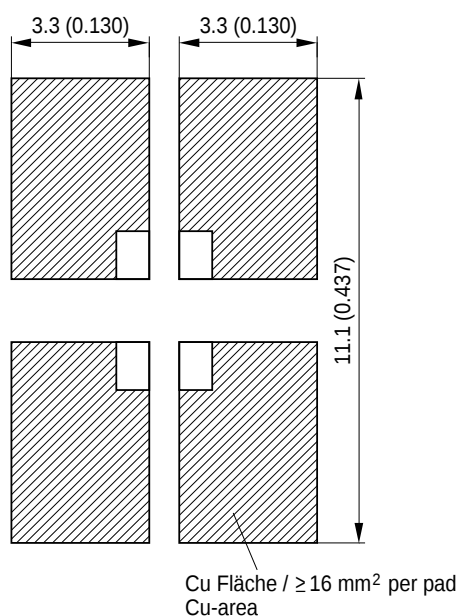
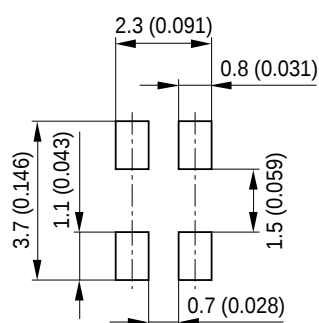
Approximate Weight:

37 mg

Recommended Solder Pad

Reflow Soldering

Padgeometrie für
verbesserte Wärmeableitung
Pad design for
improved heat dissipation



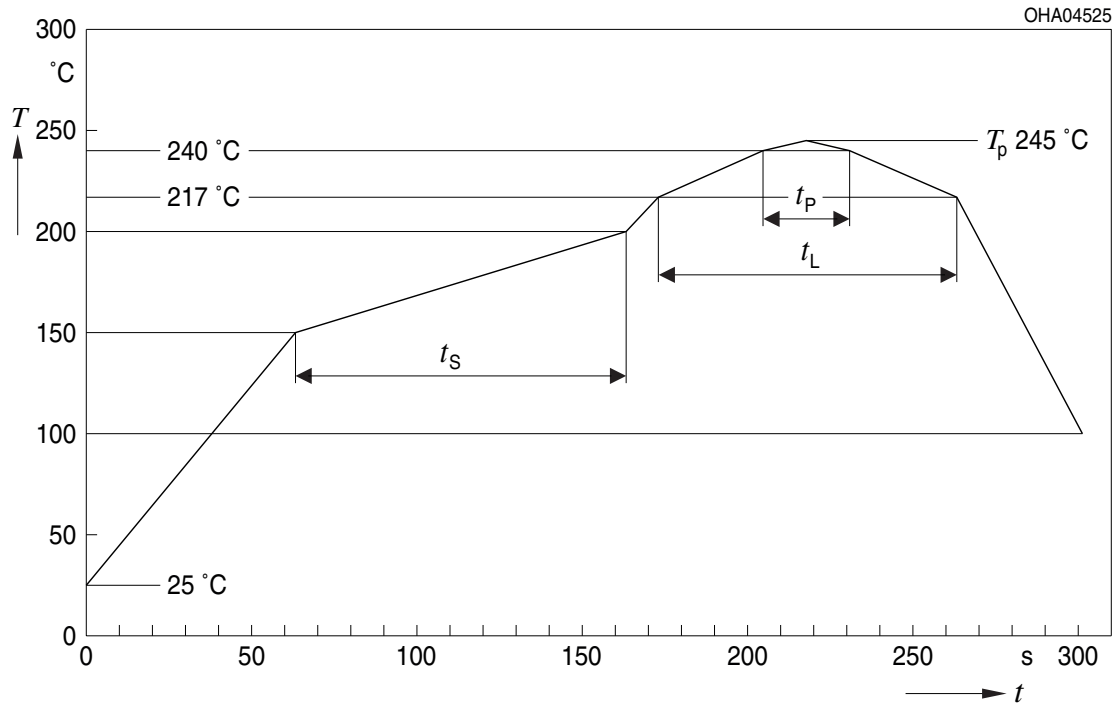
Lötstoplack
Solder resist

OHFP3021

Dimensions in mm (inch).

Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020D.01

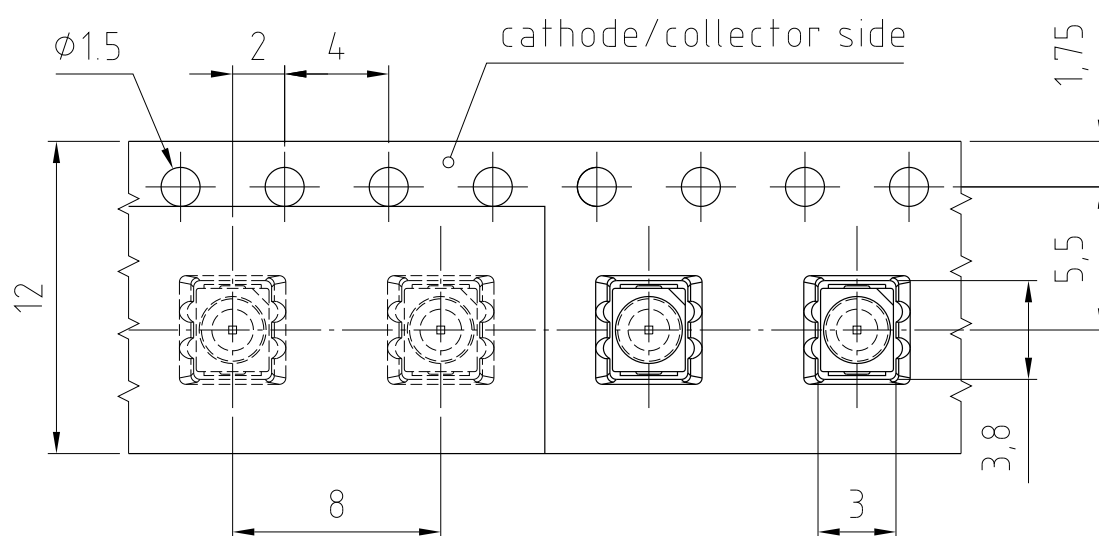


Profil-Charakteristik Profile Feature	Symbol Symbol	Pb-Free (SnAgCu) Assembly			Einheit Unit
		Minimum	Recommendation	Maximum	
Ramp-up Rate to Preheat*) 25 °C to 150 °C			2	3	K/s
Time t_s T_{Smin} to T_{Smax}	t_s	60	100	120	s
Ramp-up Rate to Peak*) T_{Smax} to T_p			2	3	K/s
Liquidus Temperature	T_L	217			°C
Time above Liquidus temperature	t_L		80	100	s
Peak Temperature	T_p		245	250	°C
Time within 5 °C of the specified peak temperature $T_p - 5$ K	t_p	10	20	30	s
Ramp-down Rate* T_p to 100 °C			3	4	K/s
Time 25 °C to T_p				480	s

All temperatures refer to the center of the package, measured on the top of the component

* slope calculation DT/Dt : Dt max. 5 s; fulfillment for the whole T-range

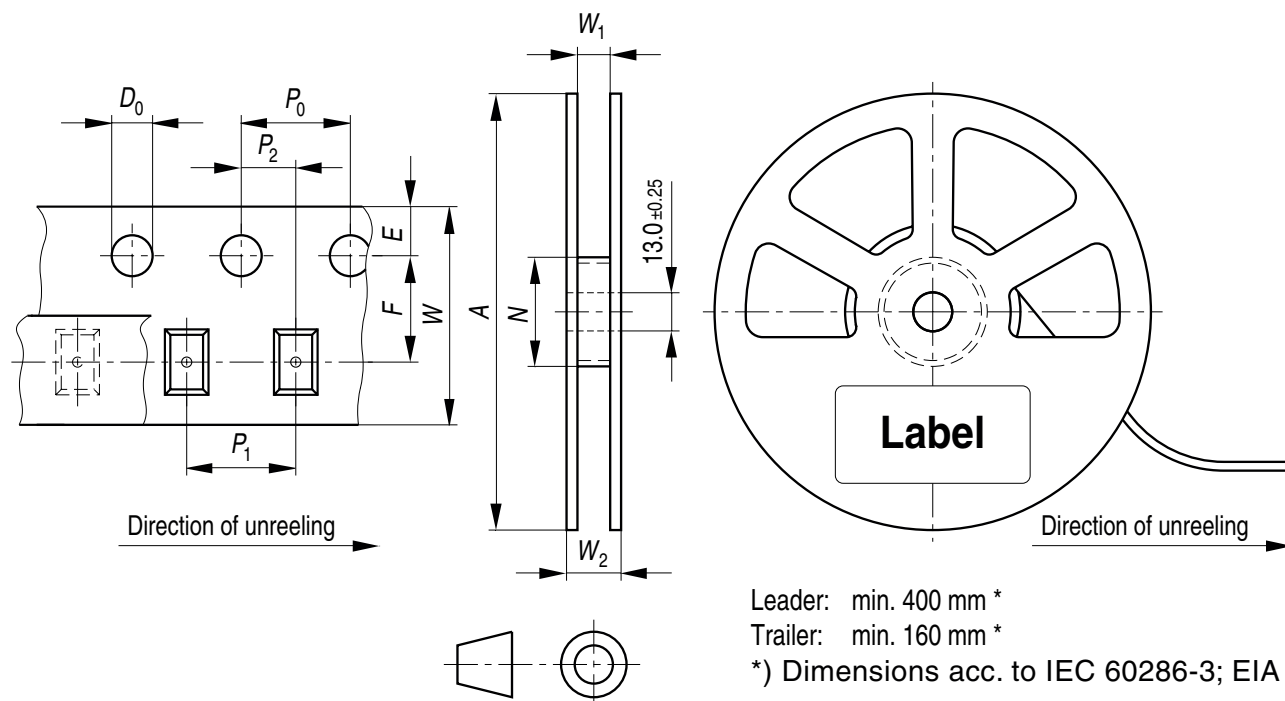
Taping



C63062-A3636-B4-03

Dimensions in mm.

Tape and Reel

12 mm tape with 2000 pcs. on $\varnothing$ 180 mm reel

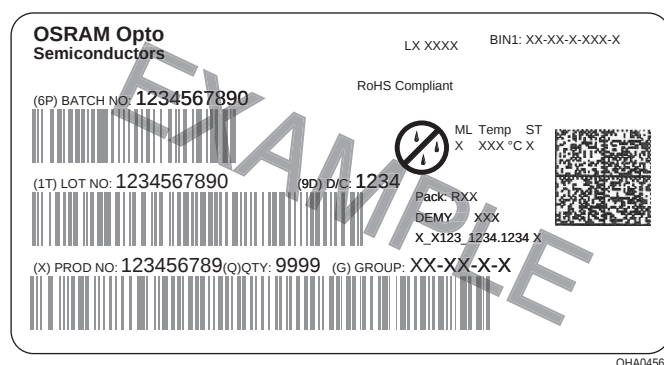
Tape dimensions [mm]

W	P ₀	P ₁	P ₂	D ₀	E	F
12 + 0.3 / - 0.1	4 ± 0.1	4 ± 0.1 or 8 ± 0.1	2 ± 0.05	1.5 ± 0.1	1.75 ± 0.1	5.5 ± 0.05

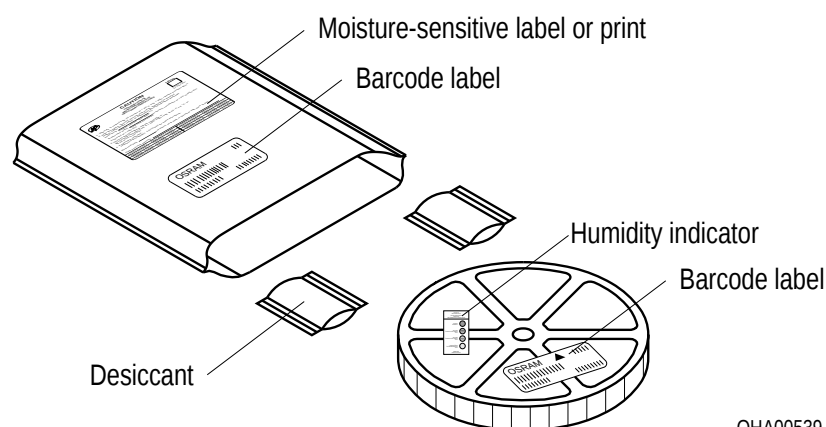
Reel dimensions [mm]

A	W	N _{min}	W ₁	W _{2max}
180	12	60	12.4 + 2	18.4

Barcode-Product-Label (BPL)



Dry Packing Process and Materials

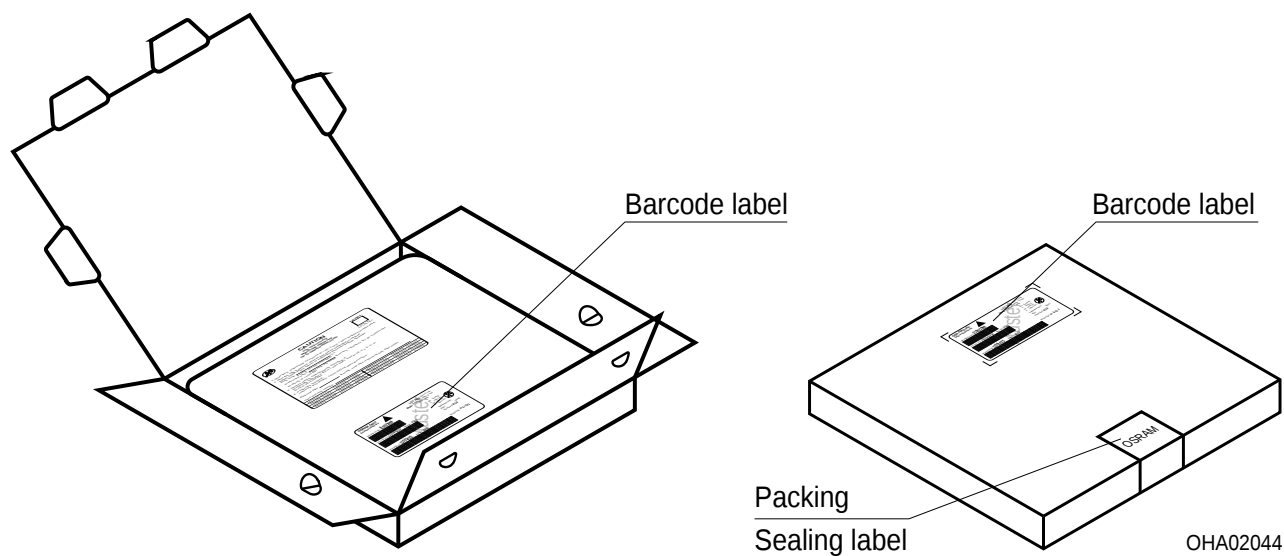


Note:

Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card.

Regarding dry pack you will find further information in the internet. Here you will also find the normative references like JEDEC.

Transportation Packing and Materials



Dimensions of transportation box in mm

Width	Length	Height
195 ± 5	195 ± 5	30 ± 5

Disclaimer

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Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version in the Internet.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office.

By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Components used in life-support devices or systems must be expressly authorized for such purpose!

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**) Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health and the life of the user may be endangered.

Glossary

- ¹⁾ **Thermal resistance:** junction -ambient, mounted on PC-board (FR4), padsize 16 mm² each
- ²⁾ **Thermal resistance:** junction - soldering point, of the device only, mounted on an ideal heatsink (e.g. metal block)
- ³⁾ **Typical Values:** Due to the special conditions of the manufacturing processes of LED, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.

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